



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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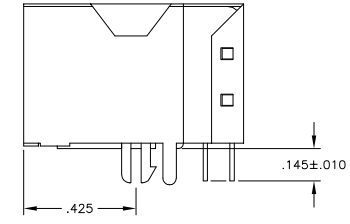
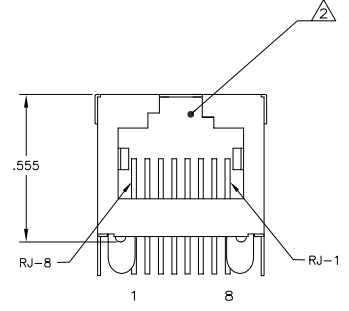
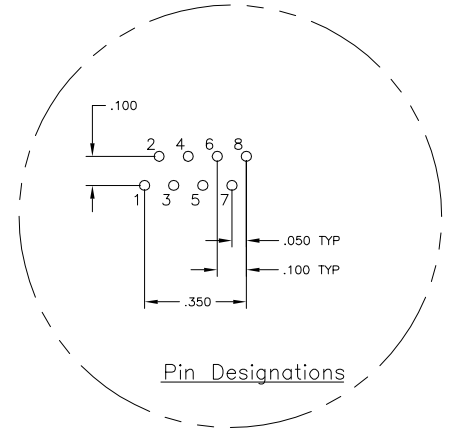
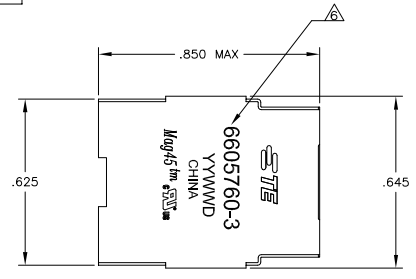
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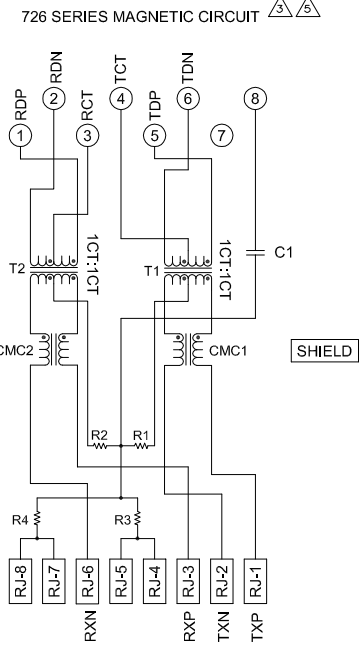
LOC	DATE	REVISIONS	DATE	BY	APP'D
AA	22				
B		REV PER ECO-08-032095	10MAR2008	VL	LR
C		ECO-11-015766	30MAY2011	EL	LR

MECHANICAL:

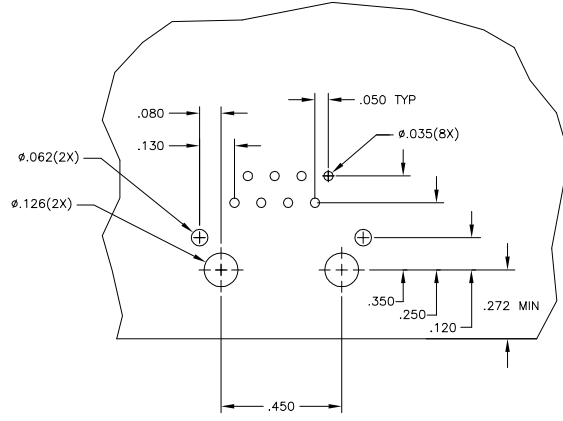


- MATERIALS:**
- HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0.
  - SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 30μINCH MIN SEMI-BRIGHT NICKEL, SOLDER TABS POST DIPPED WITH 100μINCH MIN SAC SOLDER.
  - MOD JACK CONTACTS - 0.0157" x 0.018" PHOSPHOR BRONZE, 50μINCH MIN OVERALL NICKEL UNDERPLATE, WITH SELECT 50μINCH MIN HARD GOLD FINISH PLATE. SOLDER TAILS WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP.
- RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.**
- MAGNETICS**
- IMPEDANCE: 100 OHMS
  - TURNS RATIO (CHIP CABLE): TX = 11, RX = 11
  - OPEN CIRCUIT INDUCTANCE (OCL): 350μH MIN @100kHz, 0.1VRMS, 8mADC BIAS FROM 0°C TO 70°C, TX AND RX
  - PERFORMANCE @ 25°C:
  - INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz
  - RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 30MHz
  - 18-20LOG(f/30)dB MIN FROM 30.1MHz TO 60MHz
  - 12dB MIN FROM 60.1MHz TO 80MHz
  - CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
  - 33-20\*LOG(f/50)dB MIN FROM 40.1MHz TO 100MHz
  - COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
  - ISOLATION VOLTAGE: 2250VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF 500V/SEC.
4. OPERATING TEMPERATURE: FROM 0° TO +70°C.
- INDICATED CONNECTIONS ARE FOR NIC CONFIGURATION. THE MAGNETICS ARE SYMMETRICAL, AND ARE AUTO-MDI/MDIX CAPABLE.
- TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.
7. THE PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS, PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.

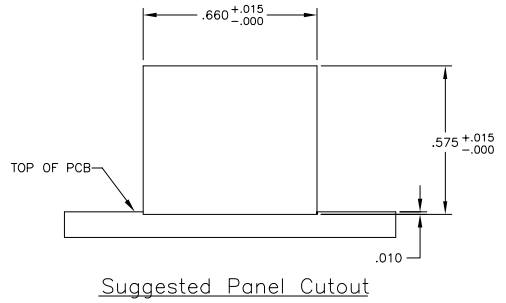
ELECTRICAL:



C1 = 1000 pF, 2kV DECOUPLING CAPACITOR  
 R1-R4 = 75 OHMS, 1/16 W RESISTORS



Suggested PCB Layout  
 (Component Side)



Suggested Panel Cutout

6605760-3  
 PART NUMBER

DIMENSIONS:		CUSTOMER SPECIFICATIONS:		MATERIAL:		FINISH:		WEIGHT:		SCALE:		SHEET:		REV:	
INCHES		MATERIAL		FINISH		WEIGHT		SCALE		SHEET		REV		C	
0 P.C. ± -		1 P.C. ± .010		2 P.C. ± .005		3 P.C. ± .005		4 P.C. ± .005		A1		00779		C=6605760	
MATERIAL		FINISH		WEIGHT		SCALE		SHEET		REV		C			